

1.2 A current limited high-side power switch with thermal shutdown

Datasheet - production data

Features

- 2.7 to 5.5 V input range
- Programmable current limit up to 1.2 A
- Low quiescent current
- Thermal shutdown
- Active-low $\overline{\text{FAULT}}$ indicator output
- 90 m Ω (typ.) ON resistance
- SO-8 and DFN8L (3 x 3 mm) packages

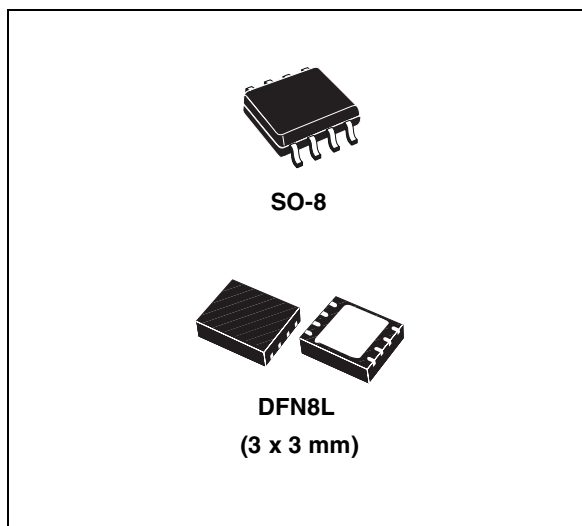
Applications

- PCMCIA slots
- Access bus slots
- Portable equipment

Description

The ST890 device is a low voltage, P-channel MOSFET power switch intended for high-side load switching applications.

The switch operates with inputs from 2.7 V to 5.5 V, making it ideal for both 3 V and 5 V systems.



The internal current limiting circuitry protects the input supply against overload. The thermal overload protection limits power dissipation and junction temperatures.

The maximum current limit is 1.2 A. The current limit through the switch is programmed with a resistor from SET to ground. The devices are available in SO-8 and DFN8L (3 x 3 mm) packages.

Table 1. Device summary

Order code	Package	Packaging
ST890BDR	SO-8	2500 parts per reel
ST890CDR	SO-8	2500 parts per reel
ST890DTR	DFN8L (3 x 3 mm)	3000 parts per reel

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1 Device summary

Figure 1. SO-8 pin connection (top view)

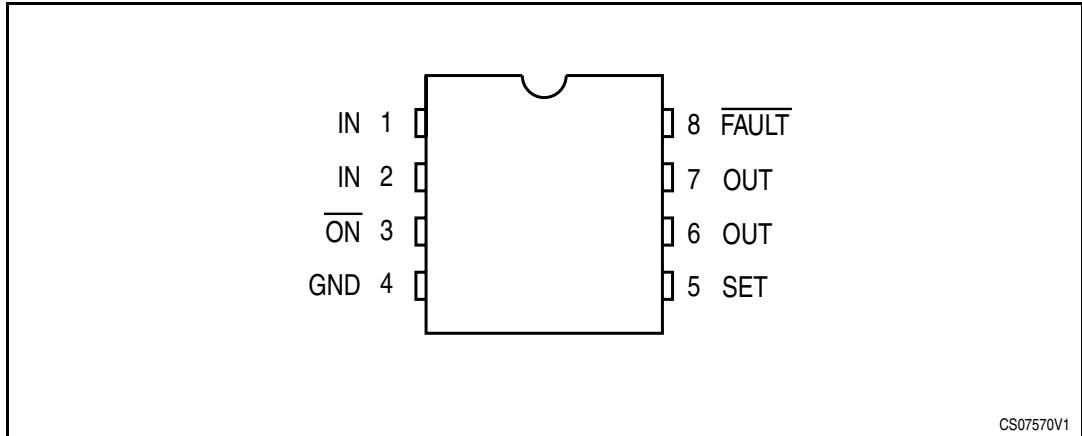


Table 2. SO-8 pin description

Pin n.	Symbol	Name and function
1, 2	IN	Input P-channel MOSFET source. Bypass IN with a 1 μ F capacitor to ground.
3	$\overline{\text{ON}}$	Active-low switch ON input. A logic low turns the switch ON.
4	GND	Ground
5	SET	Set current limit input. A resistor from SET to GND sets the current limit for the switch. $R_{\text{SET}} = 1.24 \times 1110 / I_{\text{LIM}}$, where I_{LIM} is the desired current limit in Amperes.
6, 7	OUT	Switch output. P-channel MOSFET drain. Bypass OUT with a 0.1 μ F capacitor to ground.
8	$\overline{\text{FAULT}}$	Fault indicator output. This open drain output goes low when in current limit or when the die temperature exceeds 135 $^{\circ}$ C.

Figure 2. DFN8L (3 x 3 mm) pin connection (top view)

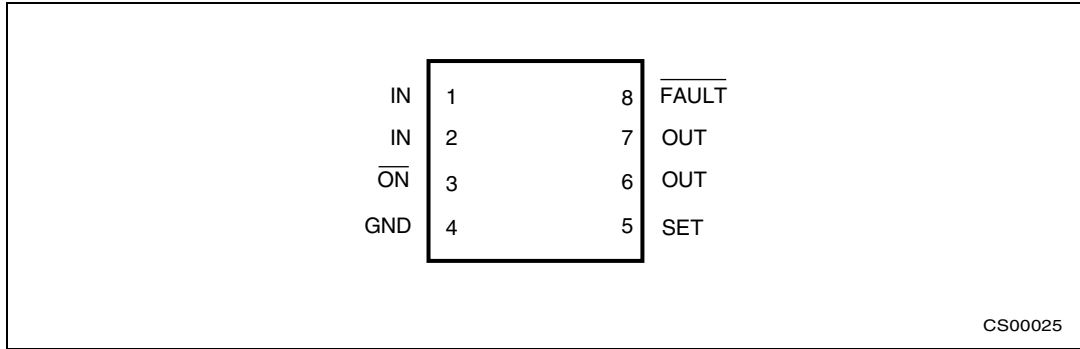
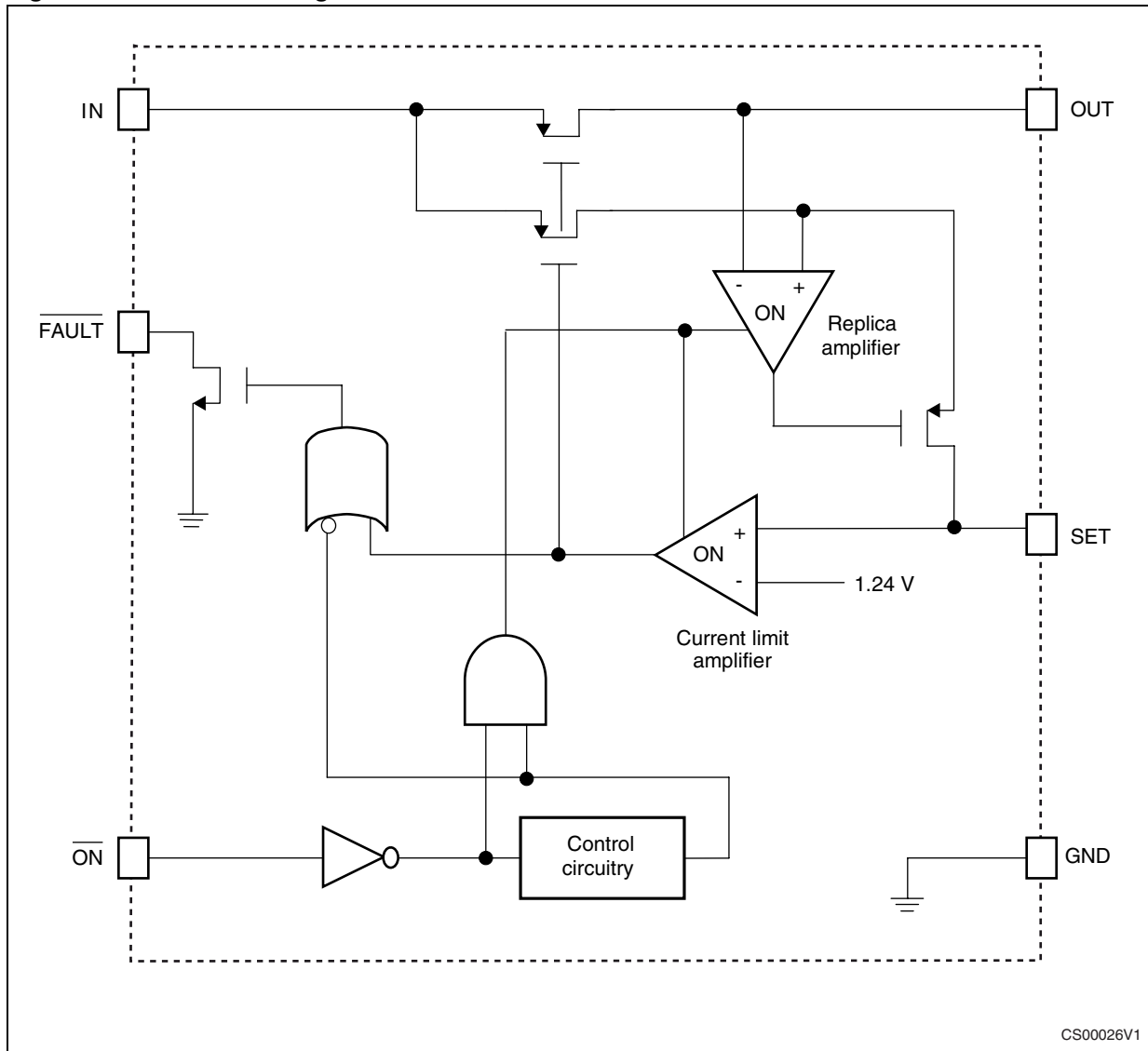


Table 3. DFN8L (3 x 3 mm) pin description

Pin n.	Symbol	Name and function
1, 2	IN	Input P-channel MOSFET source. Bypass IN with a 1 μF capacitor to ground.
3	$\overline{\text{ON}}$	Active-low switch ON input. A logic low turns the switch ON.
4	GND	Ground
5	SET	Set current limit input. A resistor from SET to GND sets the current limit for the switch.
6, 7	OUT	Switch output. P-channel MOSFET drain. Bypass OUT with a 0.1 μF capacitor to ground. $R_{\text{SET}} = 1.24 \times 1110 / I_{\text{LIM}}$, where I_{LIM} is the desired current limit in Amperes.
8	$\overline{\text{FAULT}}$	Fault indicator output. This open drain output goes low when in current limit or when the die temperature exceeds 135 $^{\circ}\text{C}$.
Exposed pad	NC	The exposed pad is not internally connected. It can be connected to PCB groundplane for best thermal performance.

Figure 3. Schematic diagram



CS00026V1

Table 4. Truth table for $\overline{\text{ON}}/\text{OFF}$ switch

$\overline{\text{ON}}/\text{OFF}$	OUT
L	ON
H	OFF

Table 5. Truth table for $\overline{\text{FAULT}}$

FAULT	FLAG
H	Normal operation
L	Fault condition

2 Maximum rating

Stressing the device above the rating listed in [Table 6: Absolute maximum ratings](#) may cause permanent damage to the device. These are stress ratings only and operation of the device at these or any other conditions above those indicated in [Table 8: Electrical characteristics](#) of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability. Refer also to the STMicroelectronics® SURE program and other relevant quality documents.

Table 6. Absolute maximum ratings

Symbol	Parameter	Value	Unit
V_I	Supply voltage	-0.5 to +6	V
V_{ON}	Input voltage at ON pin	-0.5 to +6	V
V_{FAULT_N}	Input voltage at FAULT_N pin	-0.5 to +6	V
V_{SET}	Voltage at SET pin	-0.5 to ($V_{IN} + 0.5$)	V
I_{DS}	Maximum continuous switching current	1.5	A
T_{stg}	Storage temperature	-65 to +150	°C
T_{op}	Operating ambient temperature range	-40 to +85	°C

Table 7. Thermal data

Symbol	Parameter	SO-8	DFN8L	Unit
$R_{thj-amb}$	Thermal resistance junction-ambient	160 ⁽¹⁾	37.6 ⁽²⁾	°C/W

1. This value depends from thermal design of PCB on which the device is mounted.
2. This value depends from the 4-layer PCB, JEDEC standard test board. For best thermal performance, the exposed pad PCB area should be connected by via to the PCB groundplane.

Table 8. Electrical characteristics

Symbol	Parameter	Test condition ⁽¹⁾	Value			Unit
			T _A = 25 °C			
			Min.	Typ.	Max.	
V _I	Operating voltage	I _D = 1 mA	2.7		5.5	V
I _{CC}	ON quiescent supply current	V _I = 5 V, ON = GND I _O = 0		13	25	μA
I _(CCOFF)	OFF quiescent supply current	ON = IN V _I = V _{OUT} = 5.5 V			1	μA
		ON = IN V _I = 5.5 V V _O = 0			5	
V _{ULO}	Undervoltage lockout	Rising edge	2.0	2.4	2.6	V
V _{HYST}	Undervoltage lockout hysteresis			100		mV
R _{ON}	ON resistance	V _I = 4.5 V		75	120	mΩ
		V _I = 3 V		90	130	mΩ
V _{SET}	Reference voltage to turn the switch OFF	I _O = 100 mA V _{SET} rise until V _I - V _O > 0.8 V	1.178	1.24	1.302	V
I _{MAX}	Maximum programmable output over current limit			1.2		A
I _{SC}	Short-circuit current limit	V _I = 5 V, OUT connected to GND, device enabled into short-circuit		1.2 I _{LIM}	1.5 I _{LIM}	A
I _{LIM} /I _{SET}	I _{LIM} to I _{SET} current ratio	I _O = 500 mA V _O > 1.6 V	970	1110	1300	
V _{IL}	ON input low level voltage	V _I = 2.7 to 5.5 V			0.8	V
V _{IH}	ON input high level voltage	V _I = 2.7 to 3.6 V	2.0			V
		V _I = 2.7 to 5.5 V	2.4			V
I _I	ON input leakage current	V _I = 5.5 V			1	μA
I _{SET} bias	I _{SET} bias current	V _{SET} = 1.24 V I _O = 0 A V _I = V _O		0.5	3	μA
V _{OL}	$\overline{\text{FAULT}}$ output low voltage	I _{SINK} = 1 mA V _{SET} = 1.4 V		0.15		V
I _{OH}	$\overline{\text{FAULT}}$ output leakage current.	V _{FAULT} = 5.5 V V _{SET} = 1 V			1	μA
T _{PROT}	Thermal protection			130		°C
T _{HYST}	Thermal hysteresis			15		°C

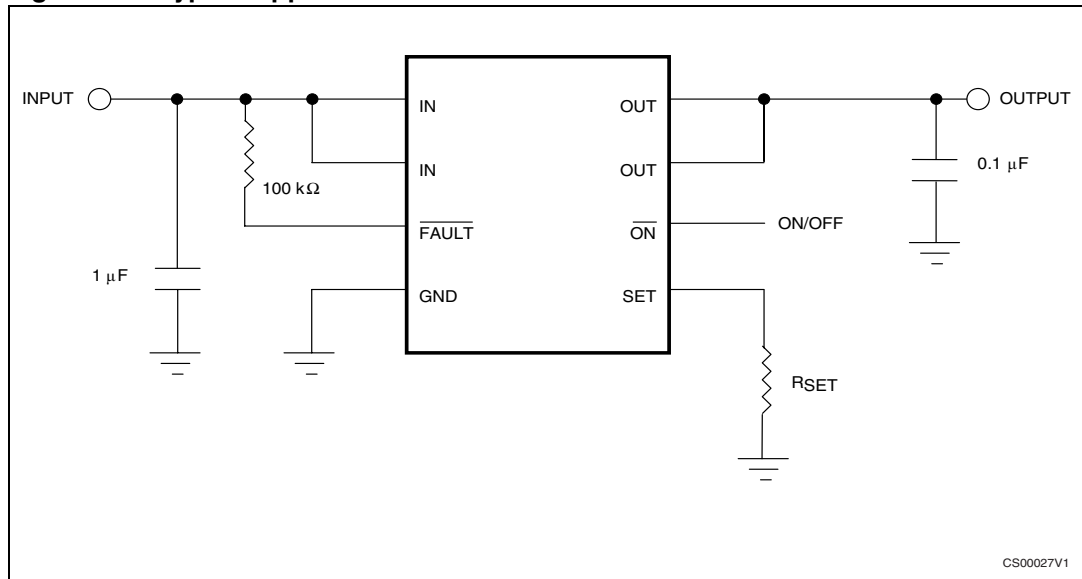
1. V_{IN} = 3 V, T_A = T_{MIN} to T_{MAX}, unless otherwise specified. Typical values are at T_A = 25 °C.

Table 9. Timing characteristics

Symbol	Parameter	Test condition ⁽¹⁾	Value			Unit
			T _A = 25 °C			
			Min.	Typ.	Max.	
t _{RESP}	Slow current loop response time	20% current overdrive, V _{CC} = 5 V		5		μs
	Fast current loop response time			2		μs
t _{ON}	Turn ON time	V _I = 5 V I _O = 500 mA		25	50	μs
		V _I = 3 V I _O = 500 mA		50		μs
t _{OFF}	Turn OFF time	V _I = 5 V	1	2	10	μs

1. V_{IN} = 3 V, T_A = T_{MIN} to T_{MAX}, unless otherwise specified. Typical values are at T_A = 25 °C.

Figure 4. Typical application circuit



2.1 Functional description

2.1.1 Output current limit

I_{LIM} is the output current that ST890 device limits under the condition V_O (output voltage) > 1.6 V.

When I_{LIM} is reached, the \overline{FAULT} pin is asserted.

2.1.2 Output short-circuit protection

The ST890 device provides short-circuit protection by limiting the output current during a short circuit event.

I_{sc} is the output short-circuit current limit level (typ. $1.2 \times I_{LIM}$). When the output is short-circuit such as $V_O < 1.6$ V, the ST890 device limits the output current to no more than the I_{sc} level.

When the output is short-circuit, the \overline{FAULT} pin is asserted.

2.1.3 Programming I_{LIM}

The ST890's I_{LIM} can be programmed through the external resistor, R_{SET} connected at the SET pin (pin 5).

I_{LIM} is determined by the following relationships:

Equation 1

$$I_{SET} = \frac{V_{SET}}{R_{SET}}$$

Equation 2

$$\frac{I_{LIM}}{I_{SET}} = 1110$$

therefore:

Equation 3

$$R_{SET} = 1.24 \times \frac{1110}{I_{LIM}}$$

2.1.4 $\overline{\text{FAULT}}$ pin

The $\overline{\text{FAULT}}$ pin (pin 8) is an open drain active-low output. This pin should be connected to an external pull-up resistor.

The $\overline{\text{FAULT}}$ pin is asserted low when:

- I_{OUT} reaches the programmed I_{LIM} value
- A short-circuit event occurs
- The device goes into thermal protection

2.1.5 Thermal protection

The ST890's thermal protection is triggered to turn off the switch when the junction temperature exceeds 130 °C (typ.).

2.2 Typical performance characteristics

Unless otherwise specified $T_j = 25\text{ }^\circ\text{C}$.

Figure 5. ON resistance vs. supply voltage

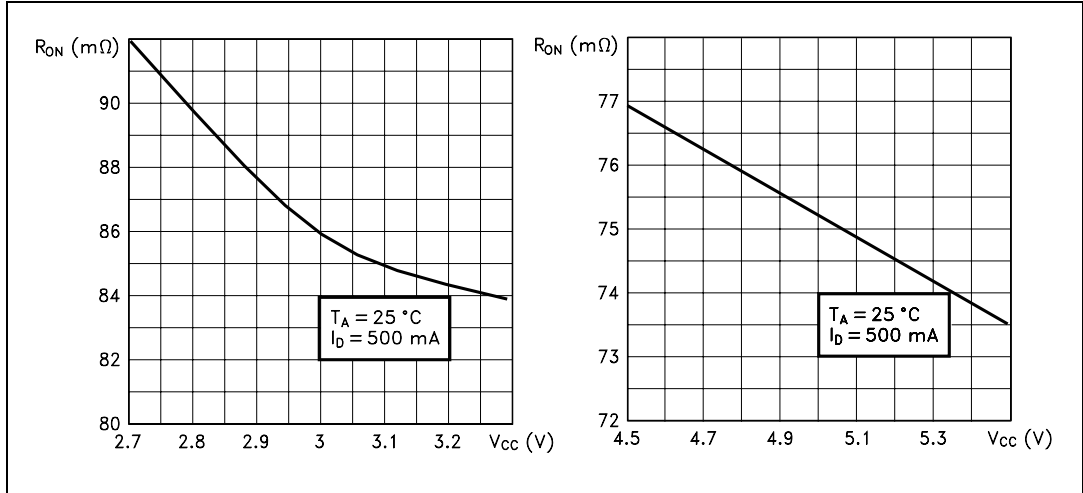


Figure 6. ON resistance vs. temperature

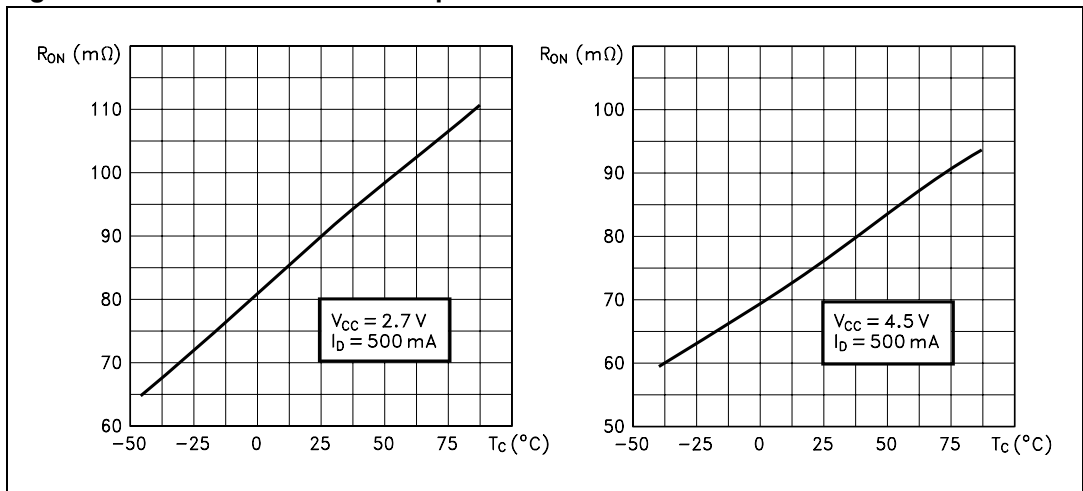
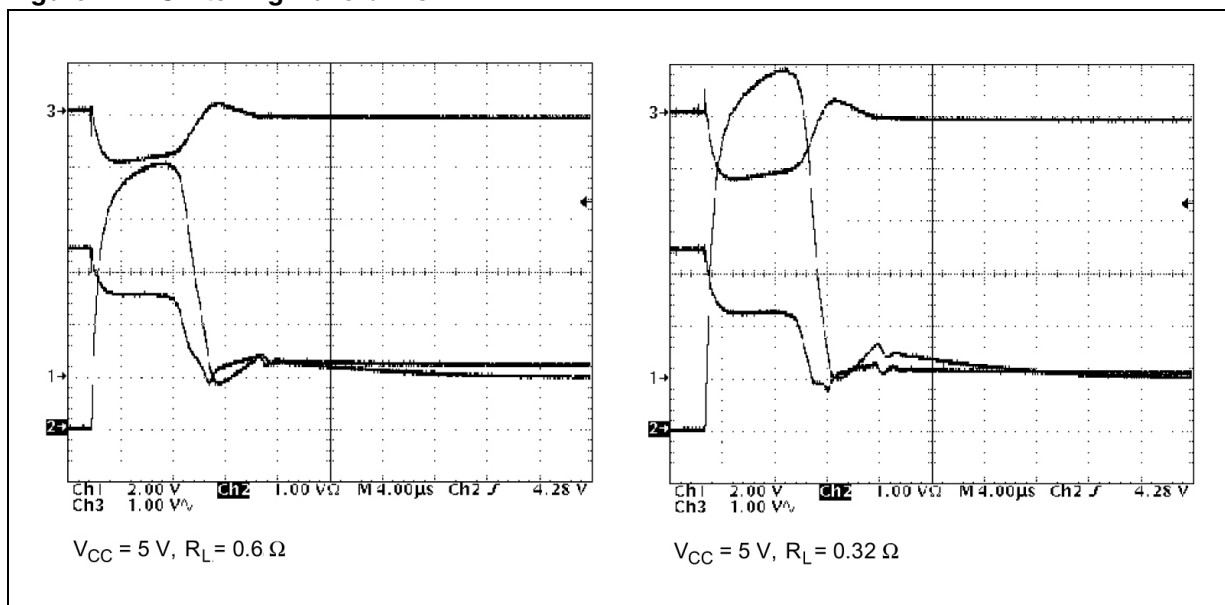


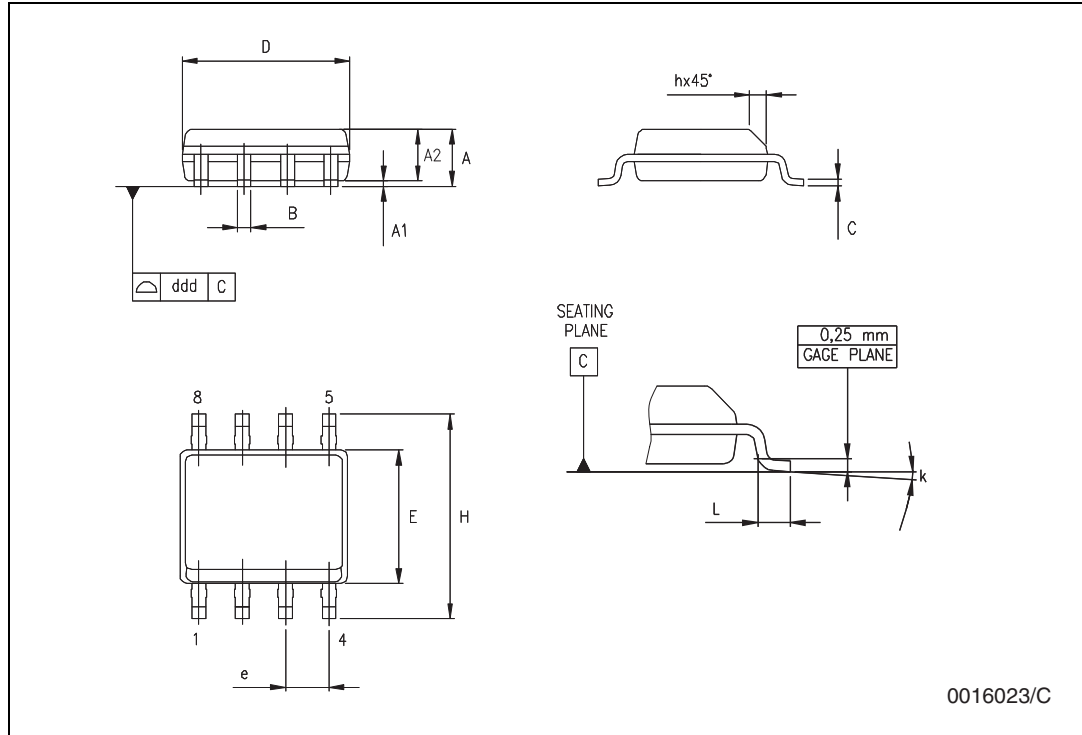
Figure 7. Switching waveforms



3 Package mechanical data

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK specifications, grade definitions and product status are available at: www.st.com. ECOPACK is an ST trademark.

Figure 8. SO-8 package outline



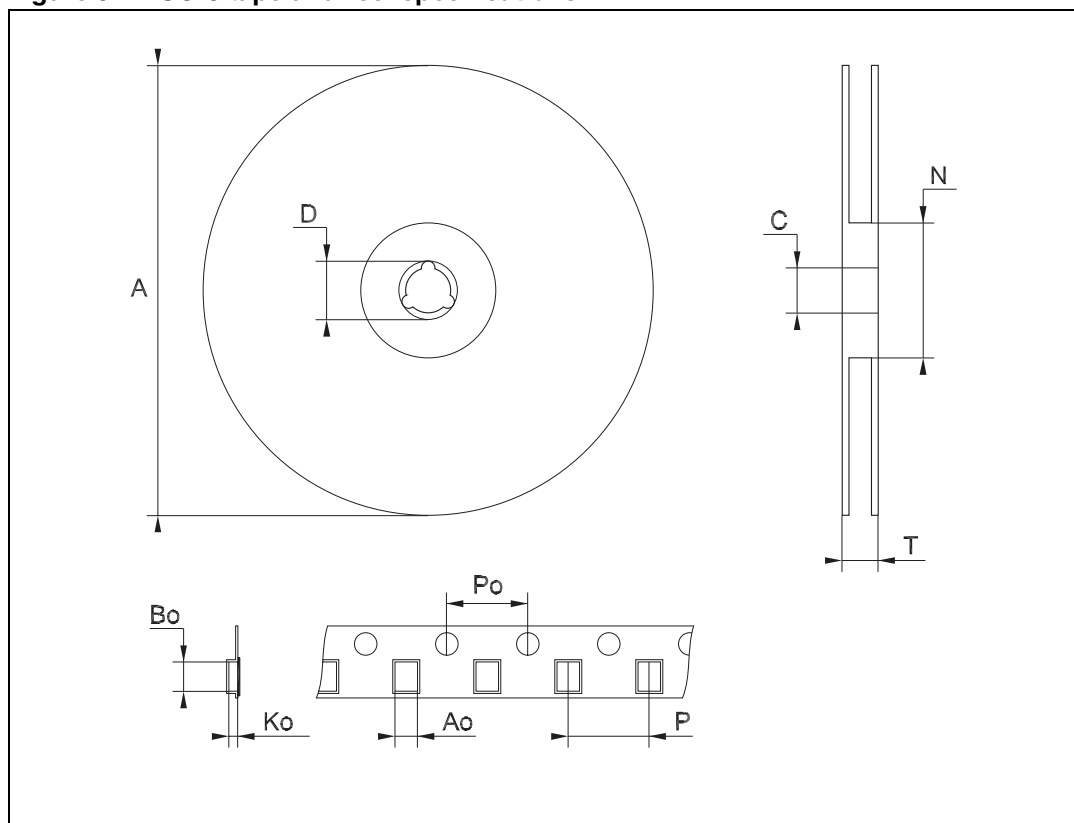
0016023/C

1. Drawing not to scale.

Table 10. SO-8 package mechanical data

Symbol	Dimensions					
	millimeters			inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	1.35		1.75	0.053		0.069
A1	0.10		0.25	0.04		0.010
A2	1.10		1.65	0.043		0.065
B	0.33		0.51	0.013		0.020
C	0.19		0.25	0.007		0.010
D	4.80		5.00	0.189		0.197
E	3.80		4.00	0.150		0.157
e		1.27			0.050	
H	5.80		6.20	0.228		0.244
h	0.25		0.50	0.010		0.020
L	0.40		1.27	0.016		0.050
k	8° (max.)					
ddd			0.1			0.04

Figure 9. SO-8 tape and reel specifications

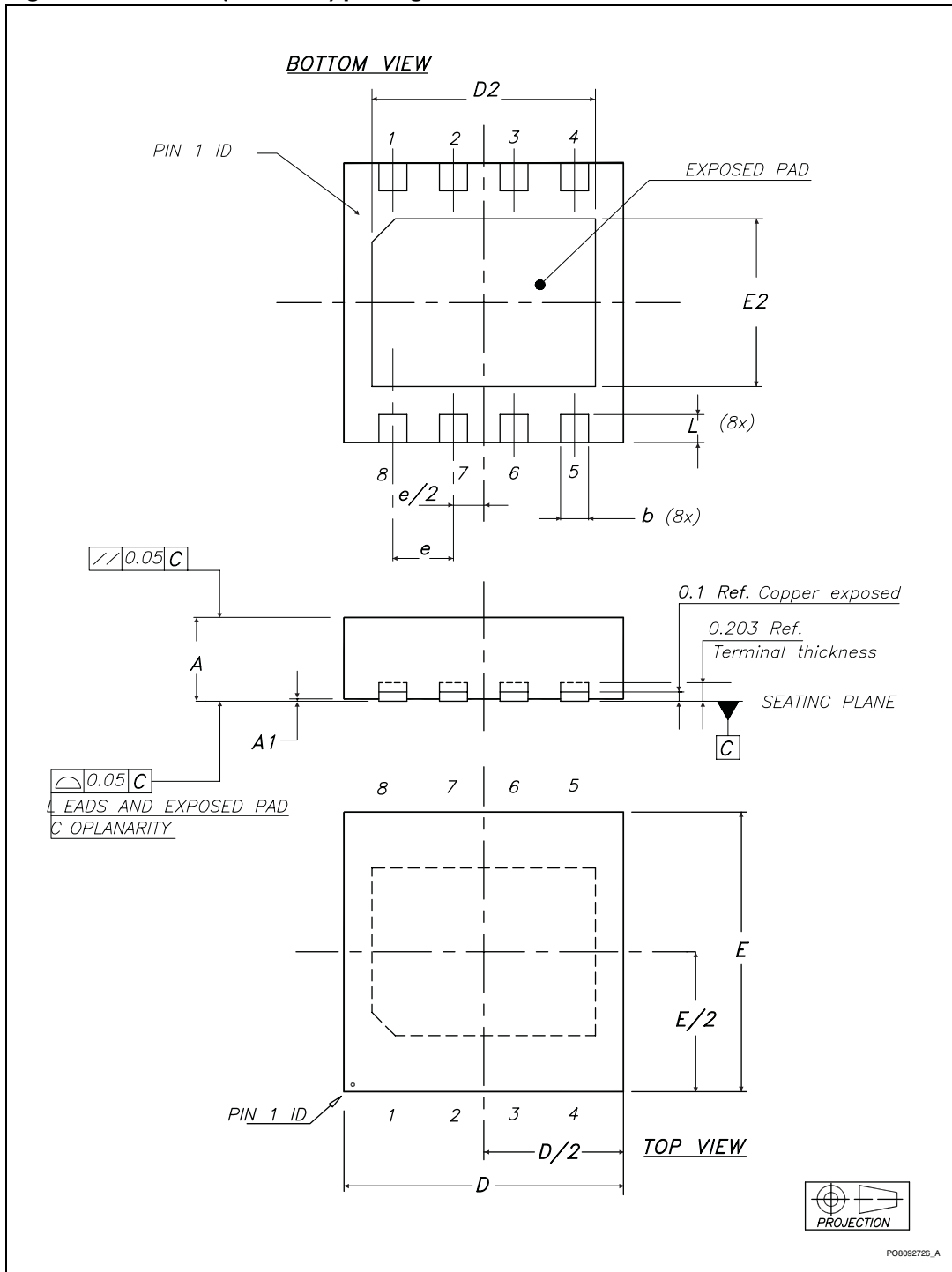


1. Drawing is not to scale.

Table 11. SO-8 tape and reel mechanical data

Symbol	Dimensions					
	millimeters			inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A			330			12.992
C	12.8		13.2	0.504		0.519
D	20.2			0.795		
N	60			2.362		
T			22.4			0.882
Ao	8.1		8.5	0.319		0.335
Bo	5.5		5.9	0.216		0.232
Ko	2.1		2.3	0.082		0.090
Po	3.9		4.1	0.153		0.161
P	7.9		8.1	0.311		0.319

Figure 10. DFN8L (3 x 3 mm) package outline

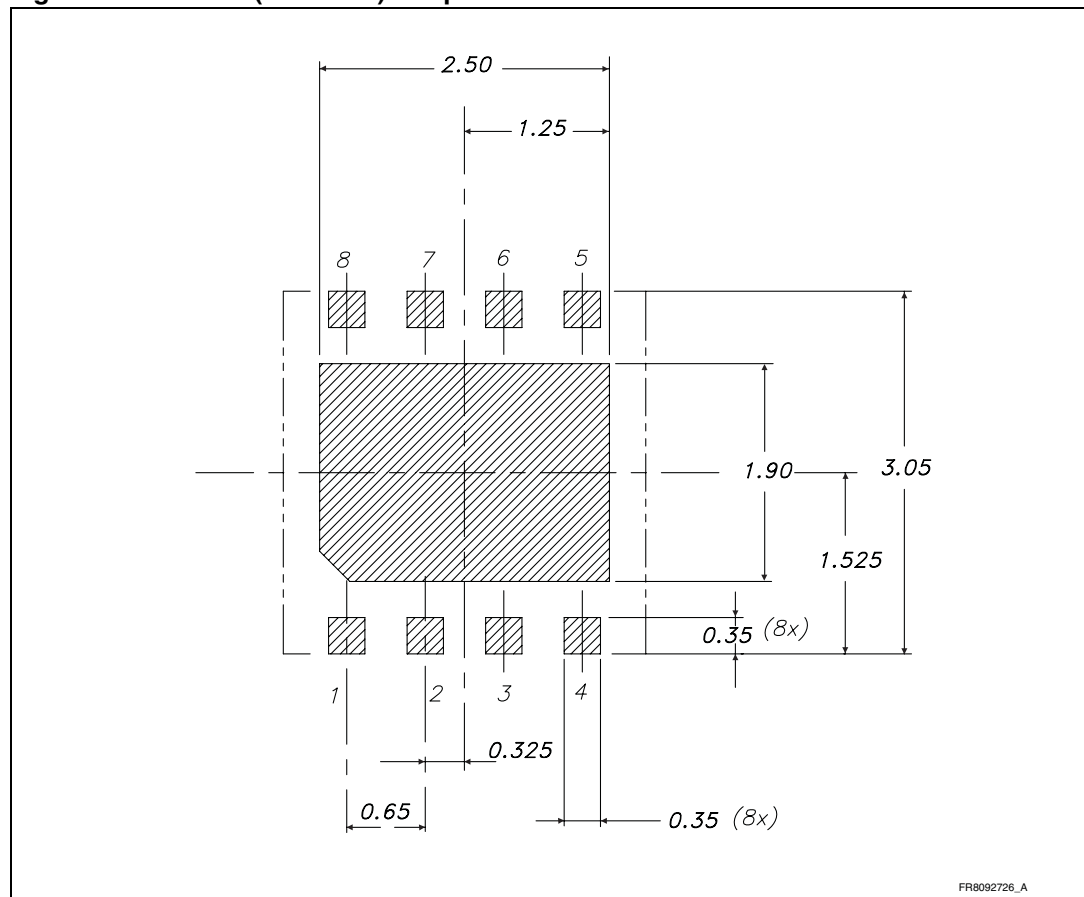


1. Drawing is not to scale.
2. Dimensions in millimeters.

Table 12. DFN8L (3 x 3 mm) package mechanical data

Symbol	Dimensions		
	millimeters		
	Min.	Typ.	Max.
A	0.80	0.85	0.90
A1	0	0.02	0.05
b	0.25	0.030	0.35
D	2.95	3	3.05
D2	2.30	2.40	2.50
E	2.95	3	3.05
E2	1.70	1.80	1.90
e		0.65	
L	0.25	0.30	0.35

Figure 11. DFN8L (3 x 3 mm) footprint recommendations



1. Drawing not to scale.
2. Dimensions in millimeters.

Figure 12. DFN8L (3 x 3 mm) tape and reel specifications

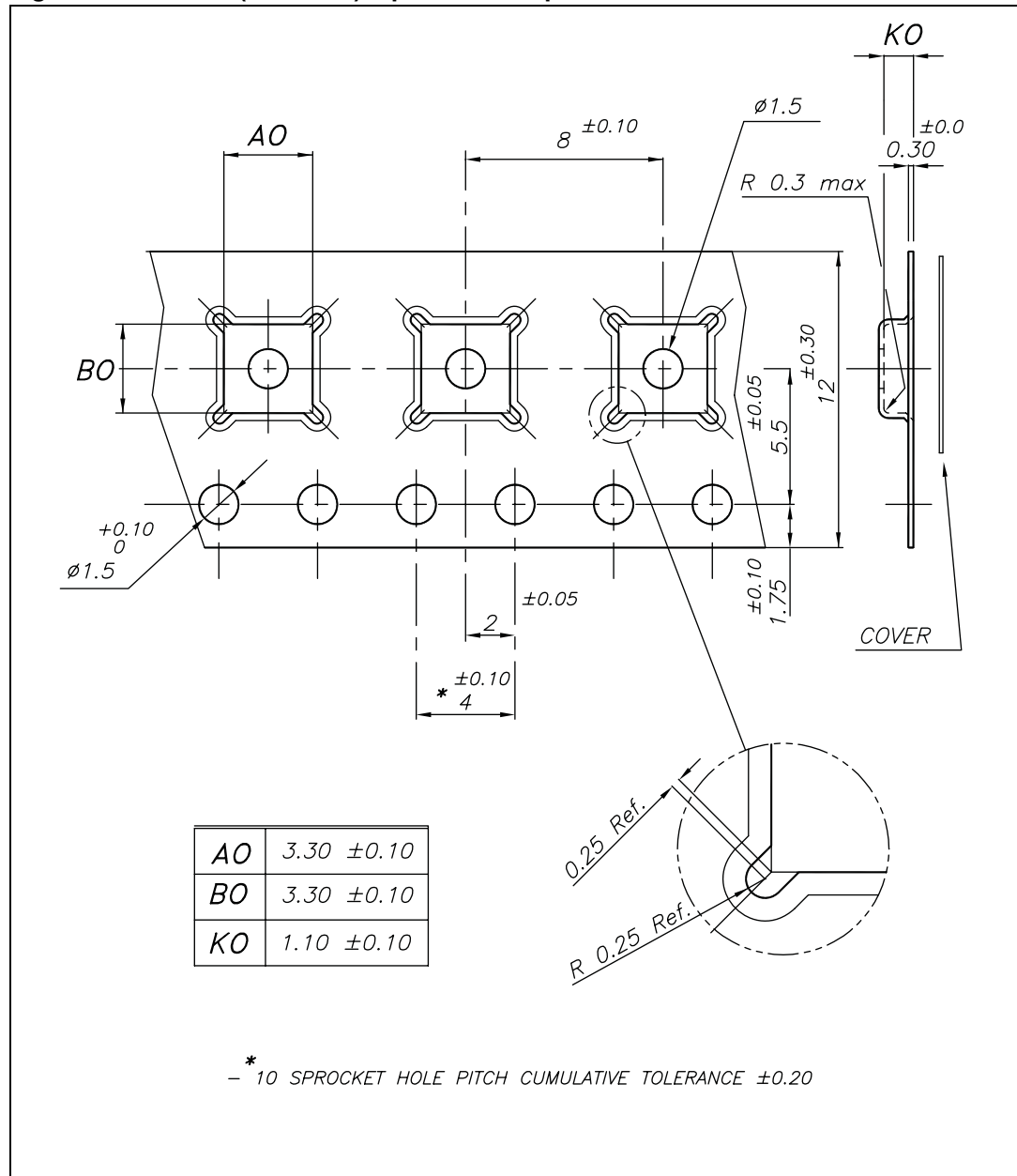
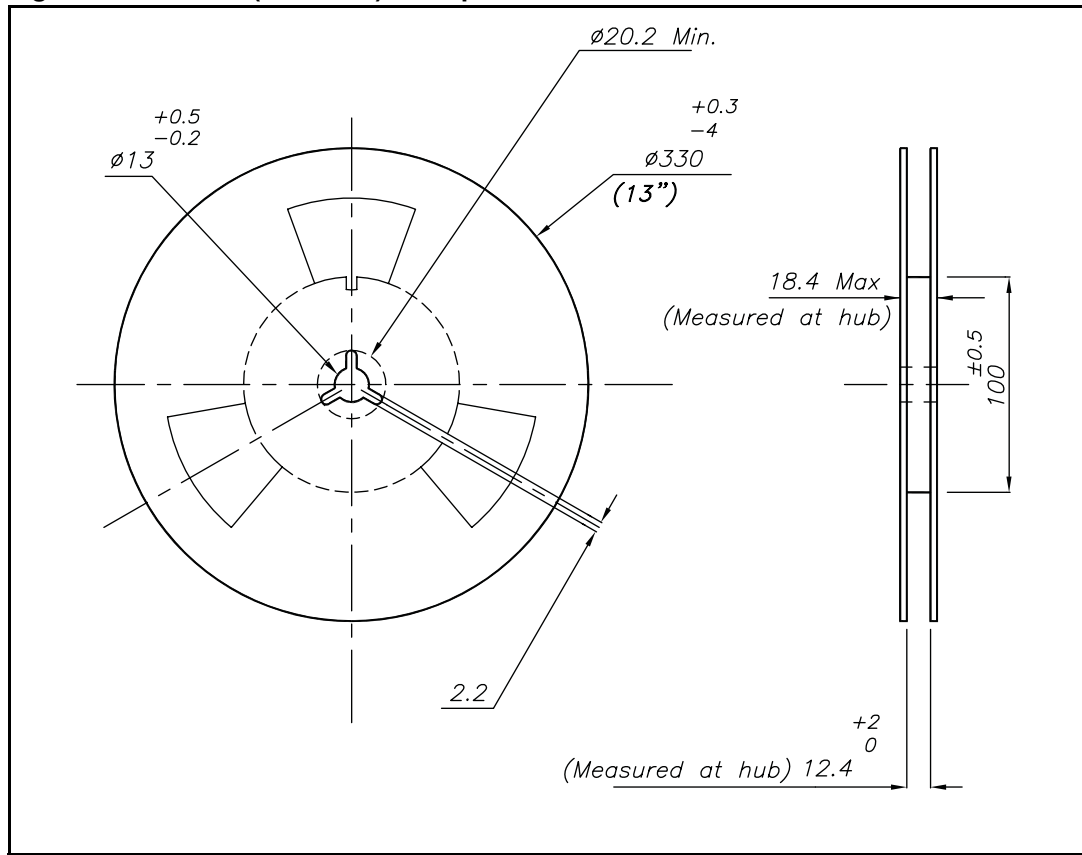


Figure 13. DFN8L (3 x 3 mm) reel specifications



4 Revision history

Table 13. Document revision history

Date	Revision	Changes
22-Jul-2005	4	Added 3 rows on Table 2 on page 3
10-Aug-2007	5	Removed ST890CD and ST890BD from Table 1 on page 1 Updated short circuit current limit value in Table 8 on page 7
1-Dec-2007	6	Added Section : Contents . Added ST890D and related DFN8L package information. Added Figure 2: DFN8L (3 x 3 mm) pin connection (top view) on page 4 . Figure 3: Schematic diagram on page 5 : redrawn, no content change. Modified title in Table 5: Truth table for FAULT on page 5 . Updated Table 8: Electrical characteristics on page 7 . Figure 4: Typical application circuit on page 8 : redrawn, no content change.
13-Oct-2008	7	Updated: Table 2 on page 3 , Table 3 on page 4 . Added: Section 2.1: Functional description on page 9 and Figure 12 on page 18 .
04-Mar-2009	8	Replaced ST890B, ST890C and ST890D with ST890. Modified: Table 6: Absolute maximum ratings
25-Jan-2013	9	Updated Figure 1 , Figure 3 , Table 5 , Section 2.1 (overlined "FAULT" and "ON" pin, minor corrections). Updated Table 3 (added "Exposed pad"). Added cross-references to Section 2 . Updated note 2. below Table 7 . Updated Table 8 (parameter of I _{OH} symbol corrected to "FAULT output leakage current"). Updated ECOPACK in Section 3 . Minor corrections throughout document.

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